



Increased Pulse Rep. Rates for Solid State Thyratron Replacements

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ICOPS



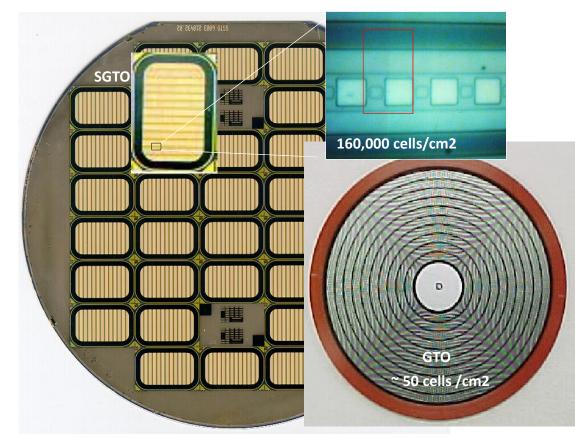
Outline

- Introduction to Solidtron's Enabling Technology
 - Pulse discharge targeted designs
- Solidtron Performance
 - Discharge Performance
 - Increased Pulse Repetition Rate Strategy/Results
- Solid State Discharge Switch Replacements
 - Motivation
 - Approach
 - Experimental results
- Summary
- Questions

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Super-GTO Vs. GTO

SGTO is an IC foundry-fabricated GTO mated with Silicon Power's proprietary low inductance ThinPak package

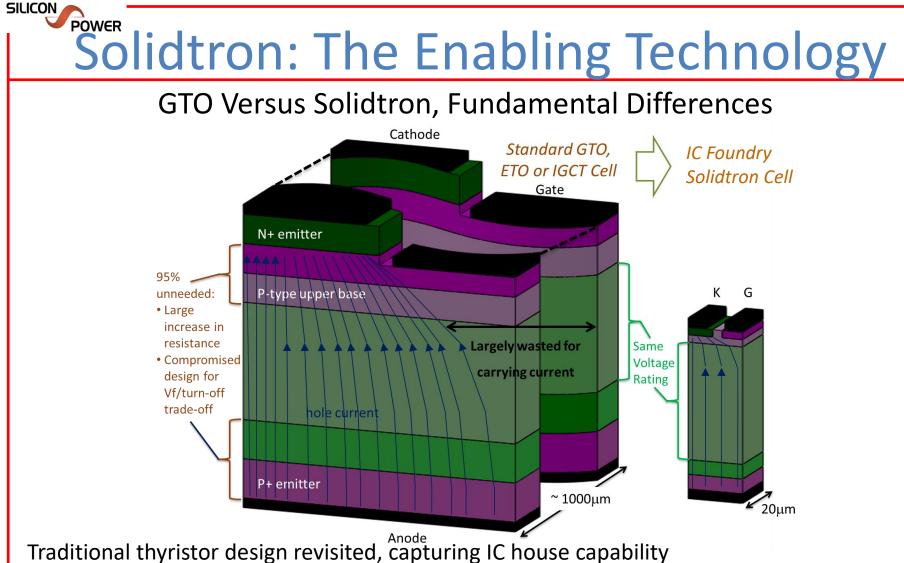


SGTO Advantages:

Cell structure 3000 x denser Upper transistor >100x improved

- Forward drop greatly reduced
- Three times lower turnoff switching loss
- Turn-on improved by 2 orders of magnitude

Die sizes from 3x3mm to 15x22mm in 200mm IC foundry providing very high yield, repeatability and uniformity!

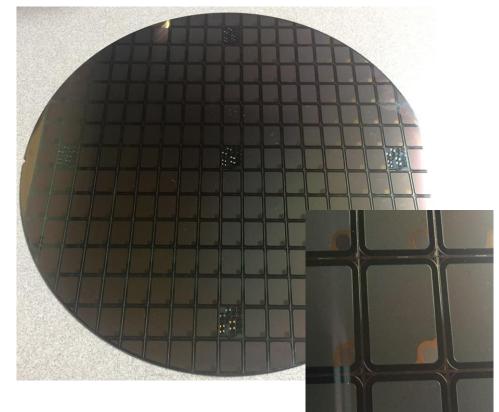


• Higher cell density improves current uniformity, drastically improving di/dt capability

- Upper base doping profile improved for higher gain
- Metal interconnects improved, increased upper transistor gain and electrode bonding area

Solidtron Vs. Super-GTO

Solidtron follows SGTO strategy, focusing on pulse discharge versus turn-off applications



Solidtron Advantages

- Cell density further enhanced
- Emitter area maximized
- Internal metal interconnect density improved
- Upper transistor gain further improved
- Increased cathode bonding pad area

8 inch starting material and improved manufacturing process further improving yield while driving cost down

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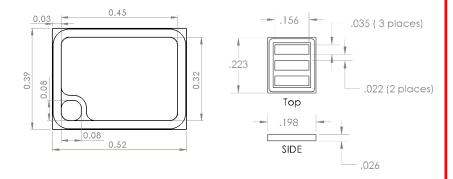
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Solidtron Performance: Hyper-Fast

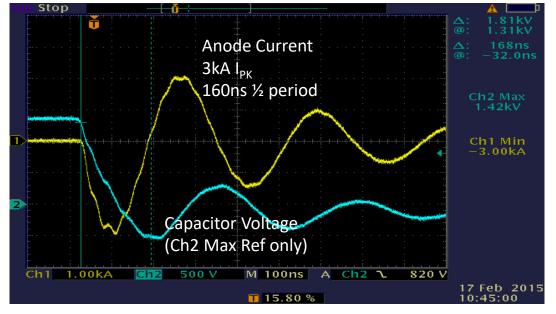
1600V Solidtron Product line:

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- Simple gating schemes (low power, easy isolation)
- Unmatched di/dt capability (>200kA/ μ s observed)
- Easily implemented in series/parallel configurations



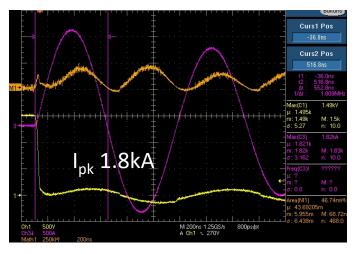
Turn-on delay	<90ns
Jitter	<500ps
Fall time	<40ns
di/dt	>200kA/µs



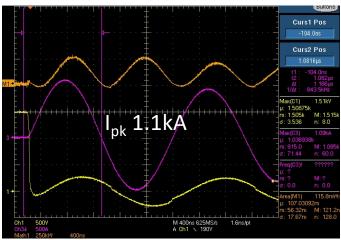
170ns ½ cycle ring down – Yellow = Anode Current, Cyan = Capacitor Voltage

Solidtron Performance: Hyper-Fast

550ns ½ pulse width ring down



 $1\mu s \frac{1}{2}$ pulse width ring down



Solid state discharge switch offers:

- Rugged yet simple gate trigger
- Repeatable fabrication and performance
- **Bidirectional current flow capability**
- Very high MTBF, minimizing down time



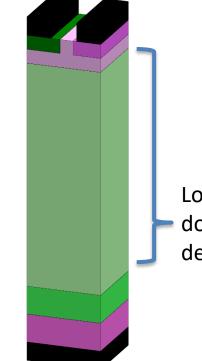
Hyper-Fast 1600V Solidtron Discrete products

Available in:

- TO-247
- TO-264
- Custom SMT packages

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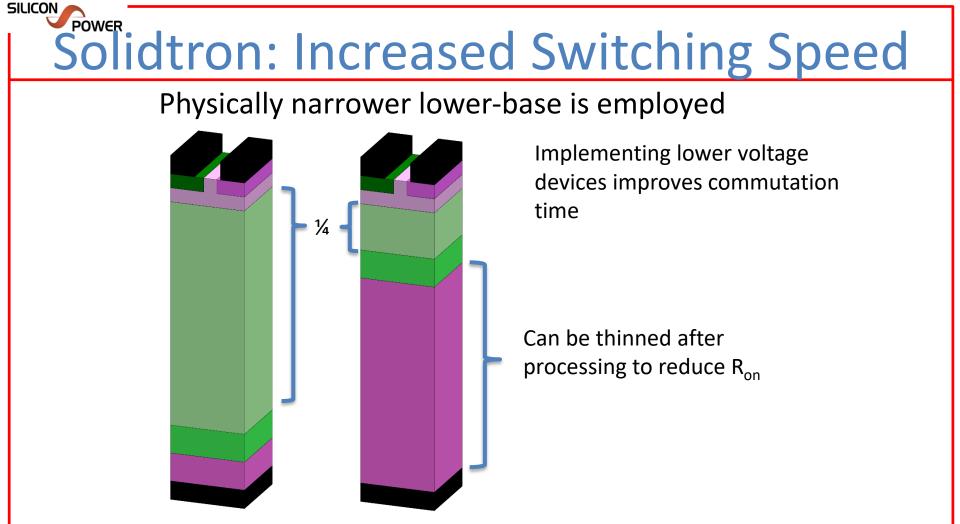
Solidtron: Increased Switching Speed



Punch-through design:

- Higher BV for given device thickness
- Allows bipolar current conduction
- Improves turn-on speed
- Reduces commutation time

Lower-base width and doping concentration determines BV



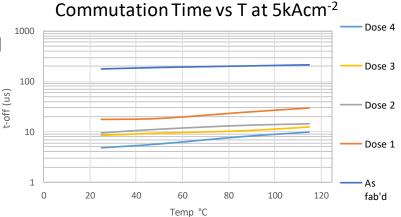
One factor contributing to commutation time is stored charge remaining in lower-base

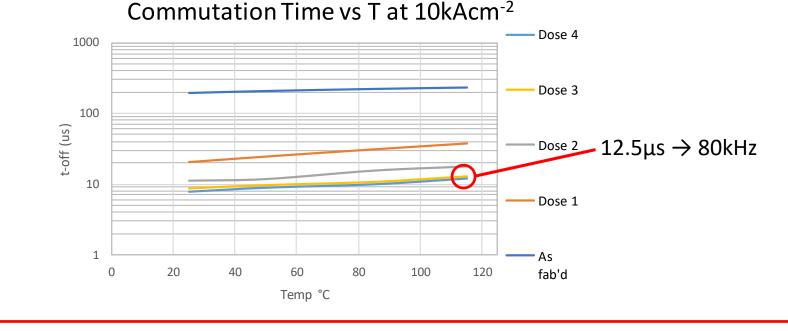
- Thinner lower-base results in less stored charge
- Thinner lower-base reduces distance required for diffused carrier to reach emitter

Post-Fabrication Speed Enhancement

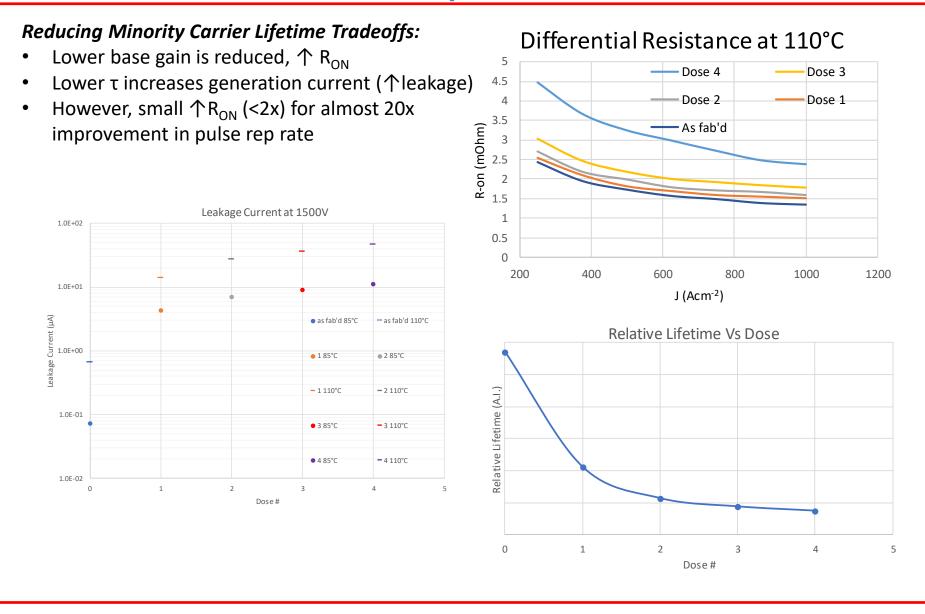
Reducing Minority Carrier Lifetime:

- Increases pulse repetition capability
 - Decreases commutation time without the need for complicated gate drive
- Post-fabrication process
 - Enables 1 design to cover range of applications ¹/₂
- Low-cost, high-volume capable process
- Demonstrated an 18x improvement in commutation time at 110°C and 10kAcm⁻²
- Favorable tradeoff for R_{on} and I_{Leakage}





Post-Fabrication Speed Enhancement



Solid State Discharge Switches

Motivation

- Compliance with RoHS
- Eliminate conditioning requirements
- Eliminate requisite heaters
- Simplify gating

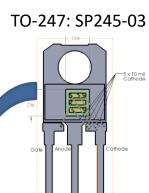
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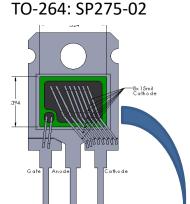
- Built in gating requires TTL/Optical trigger and DC power supply
- Improve efficiency
 - In both energy transfer and off-state conditions
- Improve turn-on delay and jitter
- Increase usable lifetime
 - No terminal erosion
- Eliminate liquid cooling requirements
- Increase mechanical installation flexibility
- Improved performance over IGBT/SCR-based solid state switch replacements

Hyper-Fast Solid State Thyratron Replacement

40kV SSTR-1 (Twin Stack)

- Initial TO-247 version demonstrated 365k pulses
 3kA, 300ns square wave
- Similar 20kV and 60kV derivatives planned to complete the product offering
- Negligible power dissipation in off-state (snubber resistors much higher in value)
- TO-264 version offers up to 30x increase in action





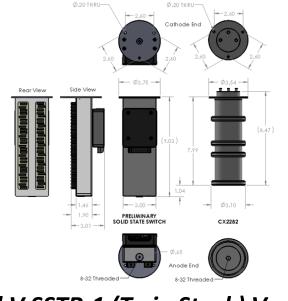


Solid State Thyratron Replacement

1 0kA

10.0k\

Ch1



40kV SSTR-1 (Twin Stack) Vs. e2v CX2282

Hyper-Fast 1600V Solidtron

- di/dt capability is >200kA/µSec
- Fiber Optically Triggered
- Small size 9" Tall, 3.75" Base diameter
- Voltage capability of 40kV

- Yellow 4.7kA Peak Current w/average di/dt of ~60kA/µSec (Circuit Limited)
- Magenta 36kV Discharge

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8.0ns/pt

Buttons

4 47ki

50.14n

n: 2.0

Summary

RoHS compliance

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- Unparalleled solid state di/dt capabilities — Hyper-fast demonstrated 200kA/µs
- f(i(t), τ) capability, determined by experimental and/or sim data exceeds most if not all commercially available gas or solid state thyratrons available
- Designed with modular, scalable sub-assemblies
 - Enables fitment for most thyratron or ignitron applications